

Call for Papers and Workshops

The *inaugural IEEE International Conference* on Additively Manufactured Electronic Systems (IEEE AMES 2025) is seeking high-quality submissions for papers (see submission options below) in all areas of technical AMES research and application. IEEE AMES 2025 offers a unique opportunity to share, discuss, and witness research results in all areas of additively manufactured electronics and their applications. Come join us in Atlanta, GA, April 2025!

General Tr	ack Topics	Workshop Topics
 Additively Manufactured Antennas and RF Printable and Flexible RF circuits 3D Printed RF Circuits Adhesive transfer antenna technology Non-conformal Arrays Wide-Area Circuit Processing Large scale manufactured systems Additively manufactured energy storage Batteries Super Capacitors 	 Additively Manufactured Optical Systems Solar cell and photodetector arrays Displays and indicators Lighting/illumination Additively manufactured packaging and interconnects Electronics packaging Printed interconnects Additively Manufactured Electronics for Computing Sensors and embedded systems Computational platforms 	 Workshop on Additively Manufactured Electronic in Space AMES applications in space Radiation hardening PaddleSats and other ultra-thin satellites Submit additional workshop proposals to the Workshops Chair at 2025.ieee-ames.org
 Important Dates Paper Submission Deadline: Januar Workshop Proposal Deadline: Januar Notification of Acceptance: March Final Paper Submission: March 31 All Deadlines are at 11:59pm 	ry 31 st , 2025 Jary 31 st , 2025 10 nd , 2025 s ^t , 2025 • Peer-Reviewed P • Posters Selected papers v Journal of Radio I	mission options apers: Full (Max. 3 pages) vill be invited to be published in Frequency Identification (JRFID)
Authors of Accepted Papers red	ceive peer reviews by General co-Chair: Emmano	S 2025 Committee

Authors of Accepted Papers receive peer reviews by top AMES technology leaders, get published on IEEE Xplore, and are enrolled in the IEEE AMES 2025 Best Paper Competition ... Don't miss out ! General co-Chair: General co-Chair: TPC Co-Chairs:

Emmanouil "Manos" Tentzeris, Georgia Tech, US Yang Yang, U of Sydney Technology, Australia Canek Fuentes-Hernandez, Northeastern U, USA Riccardo Colella, U of Salento, Italy